

L Number	Hits	Search Text	DB	Time stamp
1	1469	219/121.69.ccls. or 219/121.71.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:05
2	3	(219/121.69.ccls. or 219/121.71.ccls.) and (mechanical\$4 adj align\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:06
3	439	(219/121.69.ccls. or 219/121.71.ccls.) and (align\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:06
4	80	((219/121.69.ccls. or 219/121.71.ccls.) and (align\$8)) and (board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:06
5	0	((((219/121.69.ccls. or 219/121.71.ccls.) and (align\$8)) and (board or pcb)) and etch?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:06
6	75	((((219/121.69.ccls. or 219/121.71.ccls.) and (align\$8)) and (board or pcb)) and (metal or metallization or metallic or conducting or conductive or copper or cu or trace)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:51
8	54	(((((219/121.69.ccls. or 219/121.71.ccls.) and (align\$8)) and (board or pcb)) and (metal or metallization or metallic or conducting or conductive or copper or cu or trace)) and mask\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:07
9	68229	mask\$4 with (metal or metallization or metallic or conducting or conductive or copper or cu or trace)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:52
10	3836	(mask\$4 with (metal or metallization or metallic or conducting or conductive or copper or cu or trace)) with align\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:52
11	1705	(mask\$4 with (metal or metallization or metallic or conducting or conductive or copper or cu or trace)) with alignment	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:53
12	2	(mask\$4 with (metal or metallization or metallic or conducting or conductive or copper or cu or trace)) with (mechanical\$4 near1 alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:54
13	3347	(mask\$4 with (metal or metallization or metallic or conducting or conductive or copper or cu or trace)) with (pin or slot or tab or (side adj edge) or aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 08:55

14	74	((mask\$4 with (metal or metallization or metallic or conducting or conductive or copper or cu or trace)) with alignment) with (pin or slot or tab or (side adj edge) or aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:19
15	54	mask\$4 with trace with align\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:19
16	16	(mask\$4 with trace with align\$4) and laser\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:21
17	1682	mechanical\$4 with optical\$4 with alignment	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:26
18	61	(mechanical\$4 with optical\$4 with alignment) with advantage	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:21
19	1	((mechanical\$4 with optical\$4 with alignment) with advantage) with disadvantage	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:22
20	1	((mechanical\$4 with optical\$4 with alignment) with advantage) with pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:23
21	0	((mechanical\$4 with optical\$4 with alignment) with advantage) with slot	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:23
22	0	((mechanical\$4 with optical\$4 with alignment) with advantage) with tab	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:23
23	61	((mechanical\$4 with optical\$4 with alignment) with advantage)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:25
24	0	((mechanical\$4 with optical\$4 with alignment) with advantage) with (through-hole or opening or via or aperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:25
25	1	((mechanical\$4 with optical\$4 with alignment) with advantage) with (recess or groove)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:26

26	246	(mechanical\$4 with optical\$4 with alignment) same laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:26
27	5	((mechanical\$4 with optical\$4 with alignment) same laser) same etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/03 09:26

(FILE 'HOME' ENTERED AT 06:44:26 ON 03 FEB 2003)

FILE 'CAPLUS, INSPEC, JICST-EPLUS' ENTERED AT 06:44:47 ON 03 FEB 2003

L1 224 S MECHANICAL? ALIGNMENT?  
L2 11 S L1 AND ETCH?  
L3 9 DUPLICATE REMOVE L2 (2 DUPLICATES REMOVED)  
L4 39874 S 1 AND MASK?  
L5 16 S L1 AND MASK?  
L6 9 S L5 AND (CONDUCT? OR TRACE? OR CIRCUIT? OR METAL? OR COPPER O  
L7 7 DUPLICATE REMOVE L6 (2 DUPLICATES REMOVED)

FILE 'STNGUIDE' ENTERED AT 06:55:27 ON 03 FEB 2003

FILE 'CAPLUS, INSPEC, JICST-EPLUS' ENTERED AT 06:56:24 ON 03 FEB 2003

L8 4 S L5 NOT (L6 OR L3)  
L9 5 S L1 AND (PCB OR BOARD)  
L10 49 S L1 AND (LASER OR ABLAT?)  
L11 38 DUPLICATE REMOVE L10 (11 DUPLICATES REMOVED)  
L12 156 S L1 NOT (L10 OR L8 OR L9 OR L6 OR L2 OR L5)  
L13 135 DUPLICATE REMOVE L12 (21 DUPLICATES REMOVED)  
L14 135 FOCUS L13 1-  
L15 22 S L14 AND (CONDUCT? OR METAL? OR COPPER OR CU OR TRACE? OR CIRC